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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10007304	FILING DATE 12/05/2001	CLASS 438	SUBCLASS 629	GAU 2842	EXAMINER FAHMY
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****APPLICANTS:** Kim Ki-Bum; Soininen Pekka; Raaijmakers Ivo;
28-5

****CONTINUING DATA VERIFIED:**

**** FOREIGN APPLICATIONS VERIFIED:**
REPUBLIC OF KOREA 10-2000-0074025 12/06/2000

PG-PUB <input type="checkbox"/>	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO ASMMC.033AUS
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		
Verified and Acknowledged Examiners's initials		
TITLE : Copper interconnect structure having stuffed diffusion barrier		
U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)		

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED		
		Assistant Examiner	Total Claims	
			Print Claim for 0.0	
ISSUE FEE		Primary Examiner	DRAWING	
Amount Due	Date Paid		Sheets Drwg.	Figs. Drwg.
<input type="checkbox"/> TERMINAL		PREPARED F R ISSUE	Application Examiner	
DISCLAIMER				
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